nexperia

Final Product Change Notification	201704003F01

Issue Date: 02-Sep-2017
Effective Date: 16-Dec-2017

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Quality

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

Change of bond wire material from Au to Cu for small signal MOSFETs in SOT323

Details of this Change

Scheduled changes affect product types in SOT323 (SC-70) package only.

The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.

Old product: wire material is Au
Changed product: wire material is Cu or Au

The design and materials of all other components will remain unchanged: die, die attach, mold compound, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

Aligning with world technology standards, Nexperia continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 27-Sep-2017.

Production

Planned first shipment 01-Jan-2018

Impact

No impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
201704003A	26-Apr-2017		Change of bond wire material from Au to Cu for small signal MOSFETs in SOT323

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 02-Oct-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address   DiscrQA.Helpdesk.GA-Products@nexperia.com

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 70 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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Affected Part Number

2N7002PW,115	NX3008PBKW,115
NX3020NAKW,115	NX3008PBKW,115
2N7002BKW,115	BSS138BKW,115
BSS138PW,115	BSS138BKW,115
BSS138PW,115	NX7002AKW,115
BSS84AKW,115	NX7002AKW,115
BSS84AKW,115	2N7002BKW,115
NX3008NBKW,115	